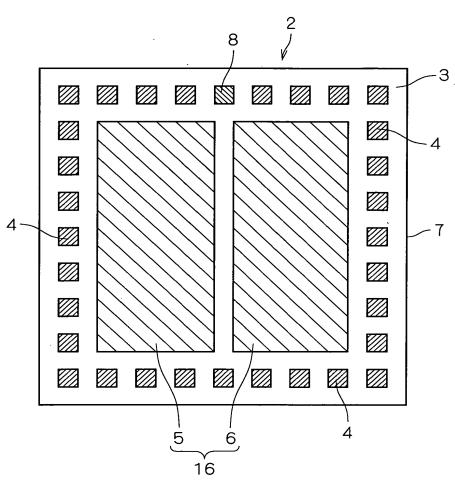
OBLON ET AL (703) 413-3000 DOCKET #_260007U S SHEET / OF8

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F | G. 1

1



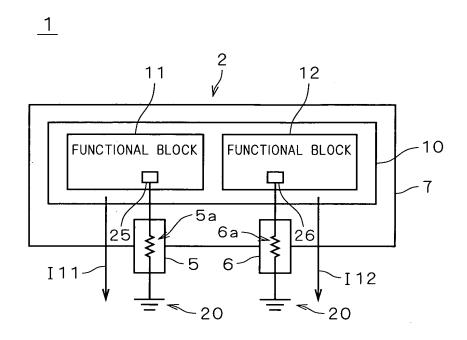
1: SEMICONDUCTOR DEVICE

2: PACKAGE
3: MOLDING RESIN
4: SIGNAL TERMINALS
5, 6, 16: GROUND TERMINALS

OBLON ET AL (703) 413-3000 DOCKET #260007US SHEET 2 OF 8

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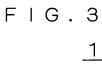
F I G . 2

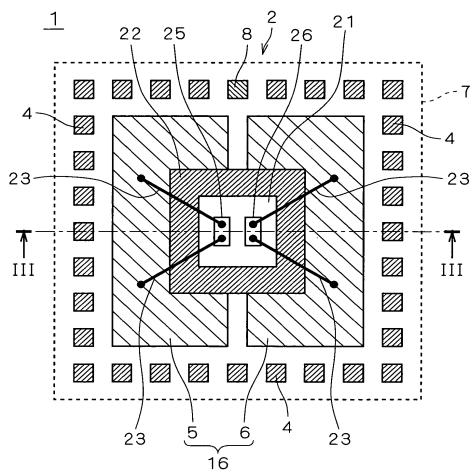


10: SEMICONDUCTOR INTEGRATED CIRCUIT

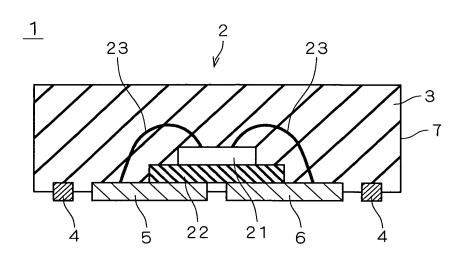
OBLON ET AL (763) 413-3000 DOCKET # **26000 TWS** SHEET **3** OF **8**

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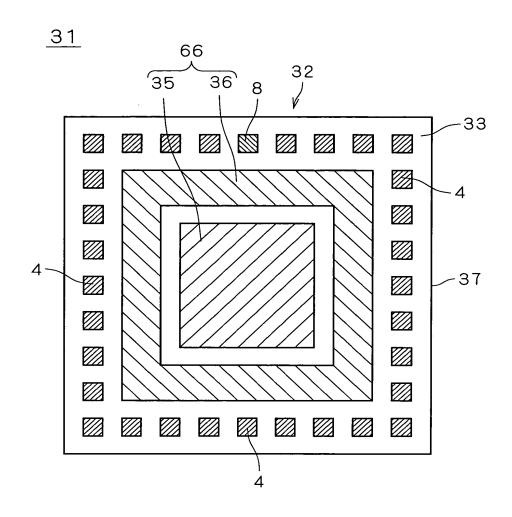
F I G . 4



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FIG.5



31: SEMICONDUCTOR DEVICE

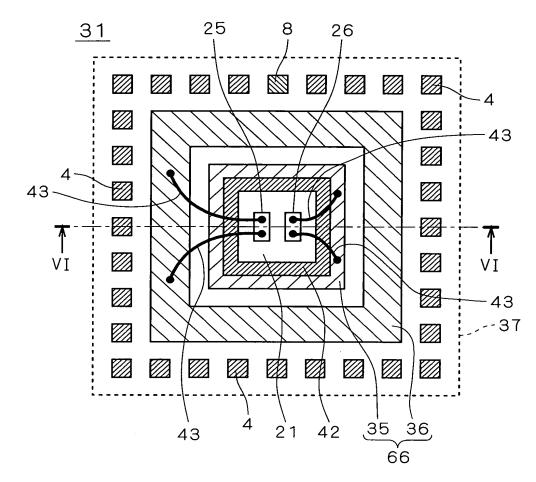
32: PACKAGE

33: MOLDING RESIN 35, 36, 66: GROUND TERMINALS

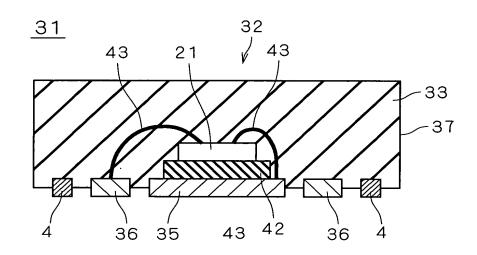
OBLON ET AL (703) 413-3000 DOCKET # 260007US SHEET 50P 8

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F I G . 6



F | G . 7

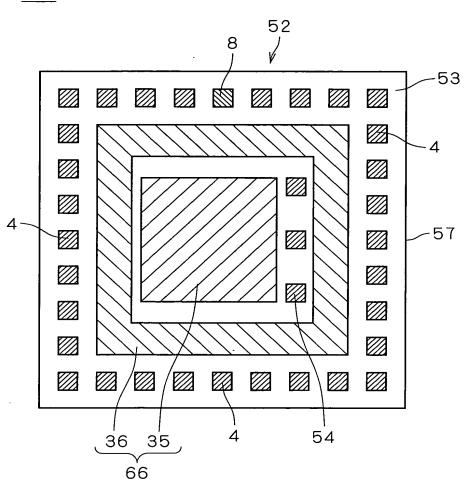


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F I G . 8

<u>51</u>



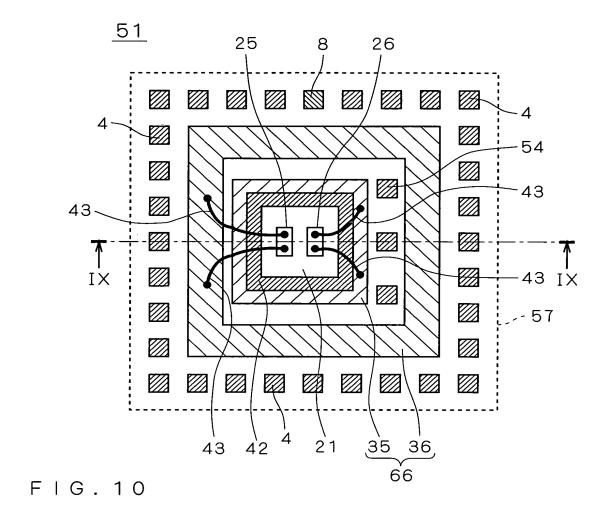
51: SEMICONDUCTOR DEVICE 52: PACKAGE 53: MOLDING RESIN 54: SIGNAL TERMINALS

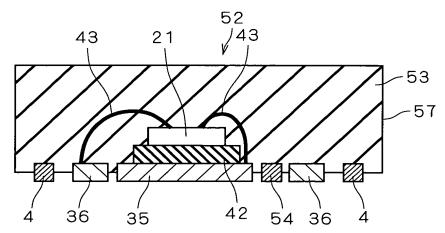
OBLON ET AL (763) 413-3000 DOCKET # 2600 7 US SHEET 7 OF 8

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F I G . 9

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OBLON ET AL (703) 413-3000 DOCKET # 2600 TUS SHEET 8 OP 8

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F I G . 11

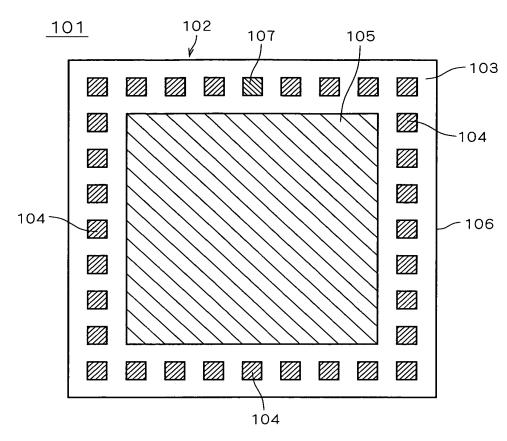


FIG. 12

